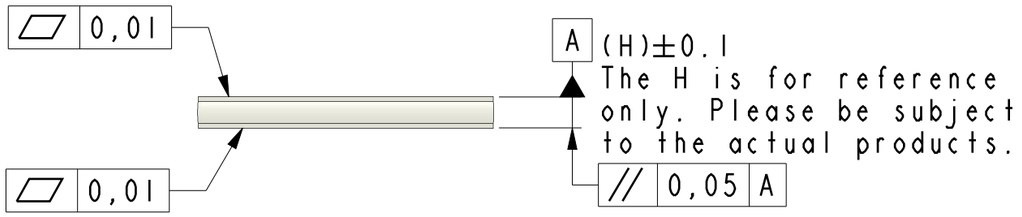
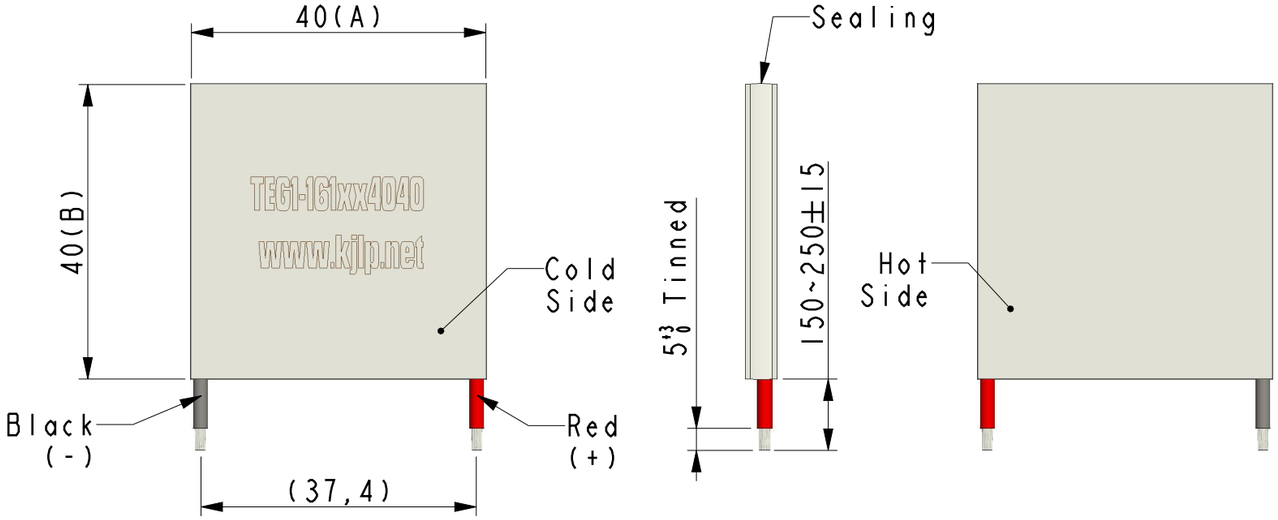
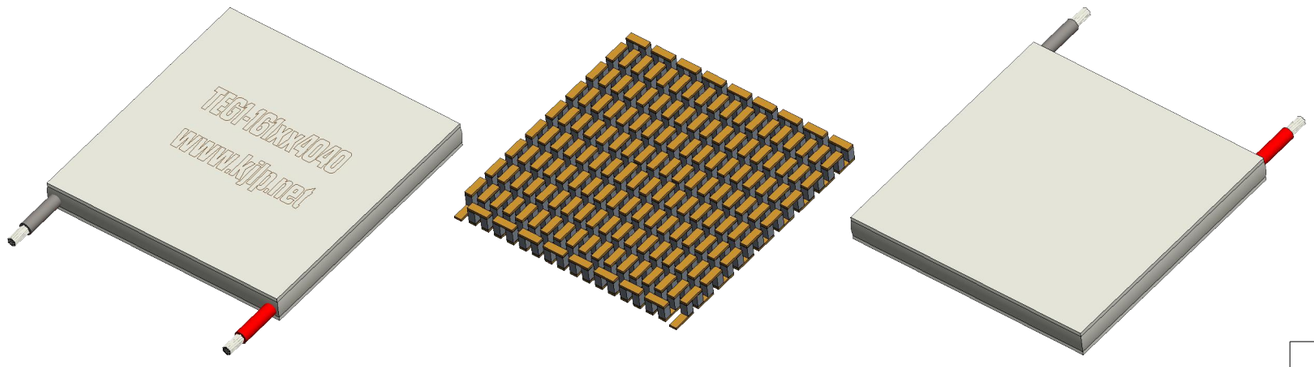
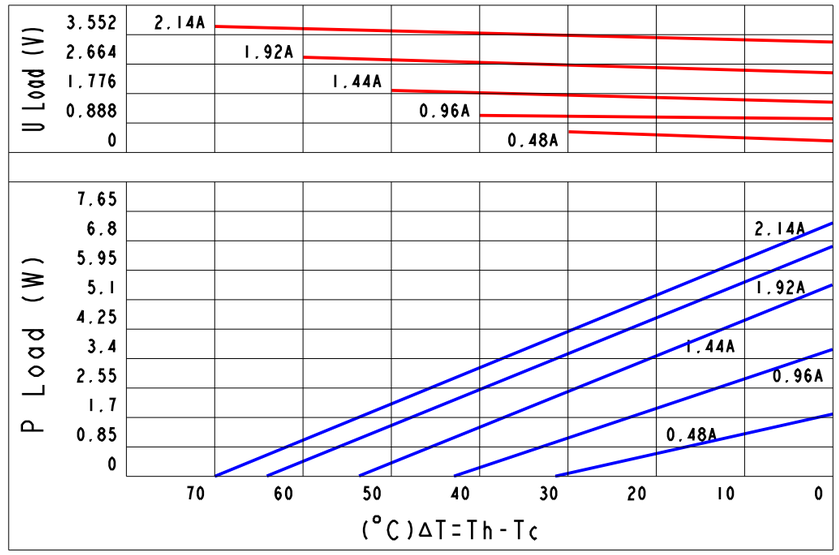
REVISIONS						
REV.	POS.	DESCRIPTION	DATE	DRW	APP	ECR#
A		INITIAL CREATION	2013/09/09	Gary	Mason	







Curve Chart(Be Confined To TEG1-161684040):



Part Number And Feature:

T	E	G	1	-	1	6	1	x	x	4	0	4	0		Sealing	YES
↓			↓		↓			↓		↓		↓			Operation Temperatur(Max.)	200°C(Max.)
Thermo Electric Chip			Stage Stack		N & P Stack Quantity			R Load		Dimension (A)		Dimension (B)			Melting Point	235°C
															Storage Temperature	-60°C~100°C
															RoHS	YES

Technical Data:

ITEM	Part NO.	Stack(P&N)	U Load(Max.)	P Load(Max.)	R Load(Max.)	Uoc	P/N Size	DIM(A)	DIM(B)	DIM(H)
1	TEG1-161684040	241	3.55 V	7.6 W	6.8 Ohm	6.7 V	2.0*1.2*1.2	40	40	RF4.2

Notes:
1. Printing always on cold side.
2. Torlerance of thermo and electric parameters ±10%.
3. Please mount heat sink before you use it as cooler. also, please do not exceed the extra voltage at any time.

1. UNLESS OTHERWISE SPECIFIED, DIMENSIONS ARE MM
2 TOLERANCE ARE AS FOLLOWS:
0 < X < 2 ± 0.06
2 < X < 10 ± 0.08
10 < X < 50 ± 0.12
50 < X < 100 ± 0.16
100 < X < 200 ± 0.20
200 < X < 300 ± 0.30
ANGLES ± 0.5°

PART No.	TEG1-161xx4040	DESCRIPTION	3.55V(Max.),7.6W(Max.), 161 P&N, 40*40mm
SIGNATURE		DATE	
DRAWN BY	Gary	2013/09/09	
CHECKED BY	Justin	2013/09/09	
ENGR	Vivi	2013/09/09	
APPROVED BY	Mason	2013/09/09	CAD MODLE: TEG1-161xx4040.prt — SCALE: 1:1 — REV: A
MATERIAL:	ISSUED BY	Jack	2013/09/09	CAD DWG: TEG1-161xx4040.drw — SIZE: A3 — SHEET: 1 OF 1

昆晶冷片（深圳）电子有限公司
KJLP (SHENZHEN)ELECTRONICS CO., LTD
email: kjlp@kjlp.net http:// www.kjlp.net
Tel: +86-755-82528352 Fax: +86-755-22639899

*DO NOT SCALE DRAWING

THIRD ANGLE PROJECTION